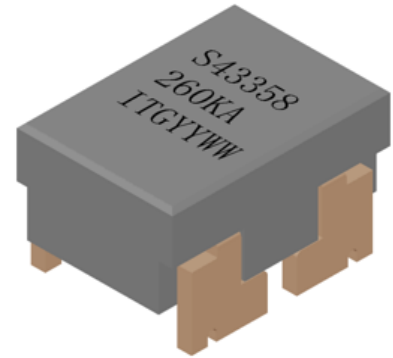


1. Features of SLA43358 Series:

- Ferrite based SMD Inductor with lower core loss.
- Inductance Range: 260.0 nH , Custom values are welcomed.
- High current output chokes, up to 51.0 Amp with approx. 20% roll off.
- Low Profile 10.00 mm Max. height.
- 11.90 x 16.60 mm Foot Print.
- Perfect for high density designs with limited board space.
- Operating frequency up to 2.0 MHz.
- Operating Temperature Range -55°C to + 130°C. RoHs & HF compliant.
- T & R Qtys: 300 pcs , 13" Reel.

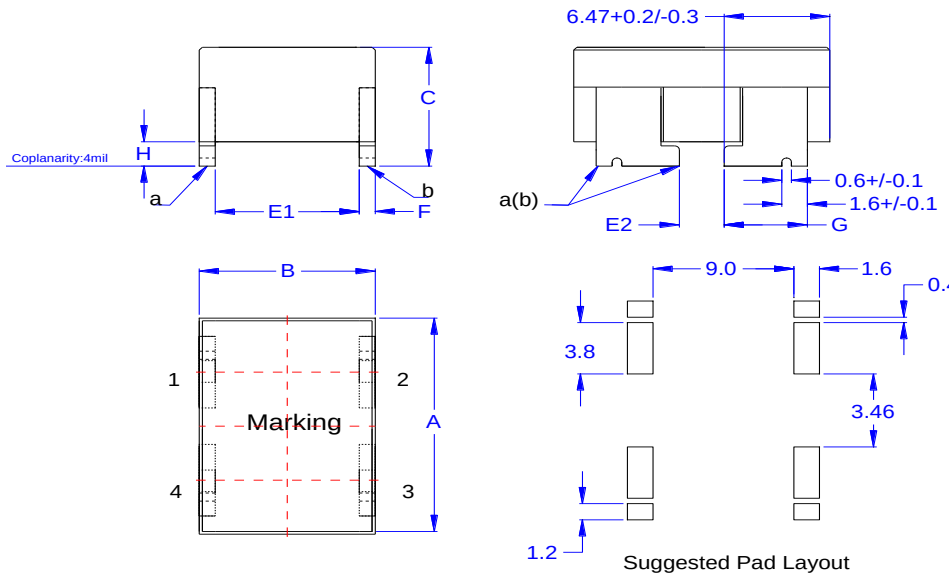


2. Electrical Characteristic of SLA43358 Series:

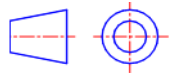
ITG Part Number	OCL(1-2&4-3) ¹ (nH) ± 10%	L @ Isat1 ² (nH) Min.	DCR(1-2&4-3) ³ (mΩ) ± 5%	Isat1 ⁴ (A) @25°C	Isat2 ⁴ (A) @100°C	Isat3 ⁴ (A) @125°C	Irms ⁵ (A) @25°C
SLA43358A-260K	260.00	182.00	0.21	51.00	47.00	45.00	51.00

3. Mechanical Dimension(Unit:mm):

A (Max.)	B (Max.)	C (Max.)	E1 ± 0.20	E2 ± 0.30	F ± 0.10	G ± 0.10	H Min.
16.60	11.90	10.00	9.70	3.66	1.00	5.20	1.60



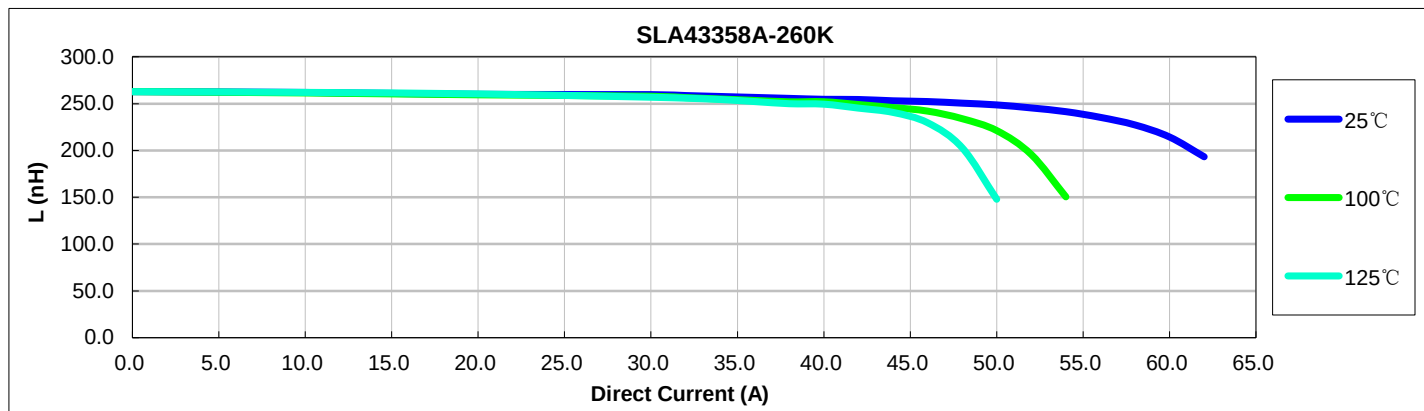
First Angle Projection:

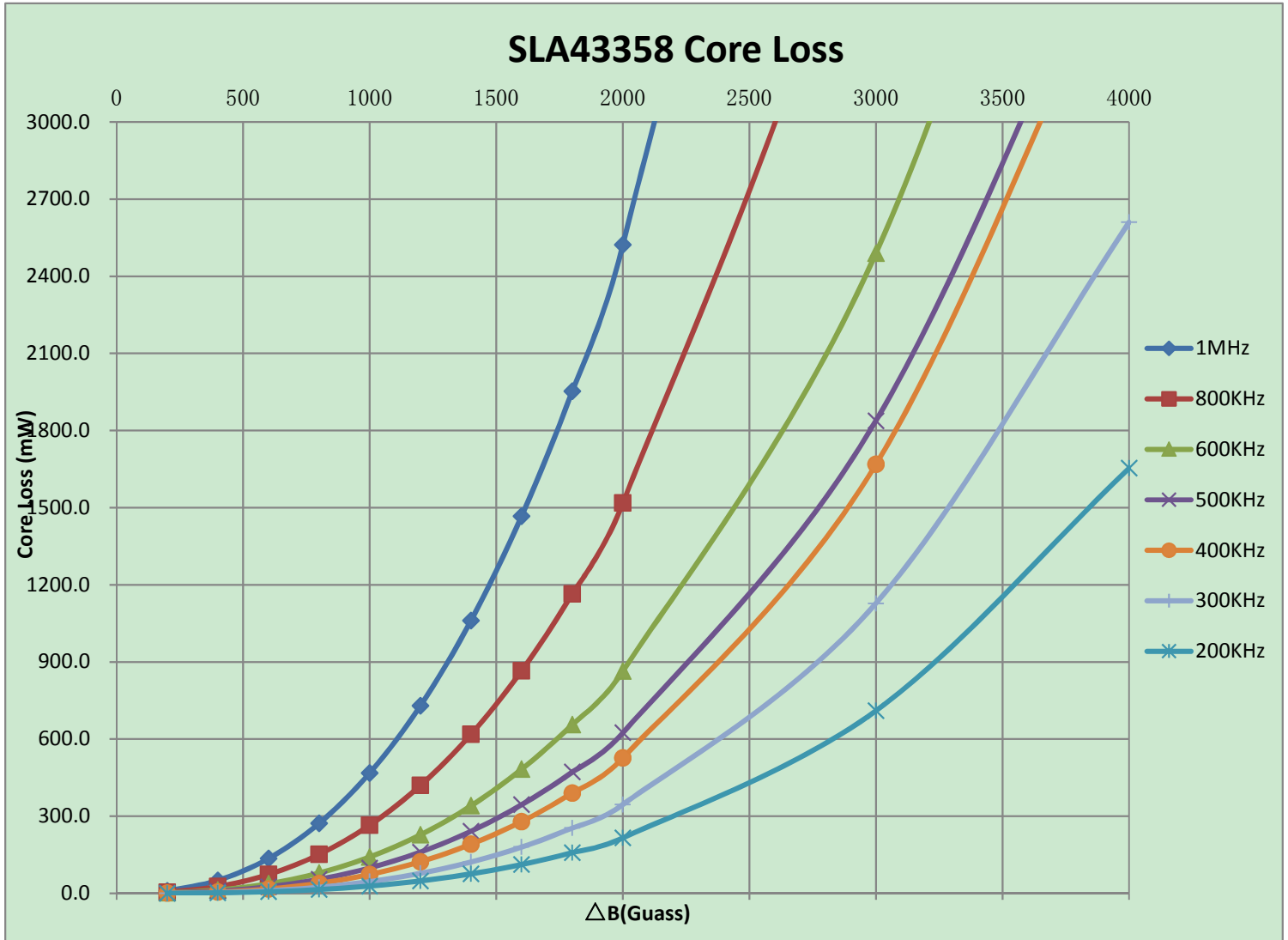


Notes:

- 1> Open Circuit Inductance (OCL) test condition: 500KHz, 0.25Vrms, 0A_{dc} at 25°C.
- 2> L @ Isat and L @ Irms Test condition: 500KHz, 0.25V_{rm} (T_a=25°C).
- 3> The nominal DCR is measured from point "a" to point "b", apply current on big terminals and voltage clip on narrow terminals, as shown above on the mechanical drawing (T_a=25°C).
- 4> Isat1, Isat2 & Isat3: DC current that will cause inductance to drops approximately by 20%.
- 5> Irms: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 130°C under worst case operating conditions as verified in the end application.

4. Inductance Characteristics (Inductance vs. Current):





Where $\Delta B = 0.0251 \cdot L(nH) \cdot \Delta I$

Soldering Reflow Chart



Stage	Precaution	Recommended temperature profile
Reflow soldering	Temperature profile can be referenced after confirming of adhesion , temperature of resistance to soldering heat , component size , soldering etc. sufficient . Note: please refer to the latest IPC/JEDEC J-STD-020: "Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices"	The graph shows Temperature in °C on the y-axis (25, 125, 220, 250, 260) and time in seconds on the x-axis. The profile starts at 25°C, ramps up to 125°C (150s to 210s), then ramps up to 220°C (240s to 480s). A shaded cyan area indicates the recommended temperature range during the 220°C ramp. The profile then peaks at 260°C for 10s (MAX) and finally cools down (Natural cooling) from 220°C.
APPROVE BY Martin	CHECKED BY Andrew	DRAWING BY Richard